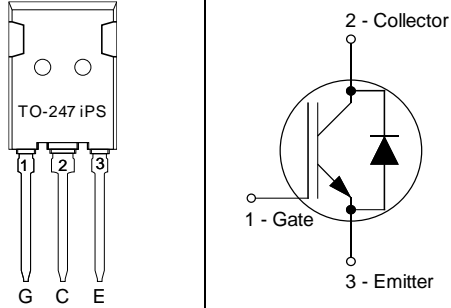


1200V 40A Trench and Field Stop IGBT

Product Information

Features <ul style="list-style-type: none"> ◆ Advanced Field Stop technology ◆ Low switching power loss ◆ Low switching surge and noise ◆ Low EMI ◆ T_{VJ} 175°C 	Package Marking and Ordering Information	
	◆ Product Name:	KJG40N120PS
Applications <ul style="list-style-type: none"> ◆ Industrial UPS ◆ Welding machine ◆ Solar converters ◆ Energy storage ◆ EV Charger 	◆ Marking:	KJG40N120PS
	◆ Package:	TO-247 iPS-3L
	◆ Quantity:	300 pcs
		

Maximum Rated Values ($T_{VJ}=25^{\circ}\text{C}$, unless otherwise specified)

Parameter	Symbol	Value	Unit
Collector-Emitter Voltage	V_{CES}	1200	V
Gate-Emitter Voltage	V_{GE}	± 20	V
Transient Gate-Emitter Voltage ($t_p \leq 10 \mu\text{s}$, $D < 0.010$)		± 30	
DC Collector Current, $T_C=25^{\circ}\text{C}$ (Limited by T_{VJ} max)	I_C	65	A
DC Collector Current, $T_C=100^{\circ}\text{C}$ (Limited by T_{VJ} max)		40	
Pulsed collector current (T_p limited by T_{VJ} max) ^[1]	I_{Cpuls}	160	
Diode Forward Current, $T_C=25^{\circ}\text{C}$ (T_p limited by T_{VJ} max)	I_F	65	
Diode Forward Current, $T_C=100^{\circ}\text{C}$ (T_p limited by T_{VJ} max)		40	
Turn-Off Safe Operating Area $V_{CE} \leq 1200 \text{ V}$, $T_{VJ} \leq 175^{\circ}\text{C}$, $t_p = 1 \mu\text{s}$	-	160	
IGBT Max. Power Dissipation	P_{D_IGBT}	420	W
FWD Max. Power Dissipation	P_{D_FRD}	300	
Operating Junction Temperature	T_{VJ}	-40 to 175	°C
Storage Temperature	T_{stg}	-55 to 150	

Thermal Characteristics

Parameter	Symbol	Min	Typ	Max	Unit
Thermal Resistance, Junction-Ambient	$R_{\theta JA}$	-	50	-	°C/W
IGBT Thermal Resistance, Junction-Case	$R_{\theta JC}$	-	0.35	-	
Diode Thermal Resistance, Junction-Case	$R_{\theta JCD}$	-	0.6	-	

Electrical Characteristics ($T_{VJ}=25^{\circ}\text{C}$, unless otherwise specified)

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Static Characteristics						
Collector-Emitter Breakdown Voltage	$V_{(BR)CES}$	$V_{GE}=0\text{ V}, I_C=0.25\text{ mA}$	1200	-	-	V
C-E Leakage Current	I_{CES}	$V_{CE}=1200\text{ V}, V_{GE}=0\text{ V}$	-	-	200	μA
G-E Leakage Current	I_{GES}	$V_{CE}=0\text{ V}, V_{GE}=\pm 20\text{ V}$	-	-	± 200	nA
G-E Threshold Voltage	$V_{GE(th)}$	$V_{CE}=V_{GE}, I_C=250\text{ }\mu\text{A}$	5.1	5.9	6.7	V
Collector-Emitter Saturation Voltage	$V_{CE(sat)}$	$V_{GE}=15\text{ V}, I_C=40\text{ A}$ $T_{VJ}=25^{\circ}\text{C}$ $T_{VJ}=175^{\circ}\text{C}$	-	1.75	2.20	V
Diode Forward Voltage	V_F	$V_{GE}=0\text{ V}, I_F=40\text{ A}$ $T_{VJ}=25^{\circ}\text{C}$ $T_{VJ}=175^{\circ}\text{C}$	-	1.7	3.0	
Dynamic Characteristics						
Input Capacitance	C_{ies}	$V_{CE}=25\text{ V}, V_{GE}=0\text{ V},$ $f=1\text{ MHz}$	-	9500	-	pF
Output Capacitance	C_{oes}		-	150	-	
Reverse Transfer Capacitance	C_{res}		-	86	-	
Gate Charge	Q_G	$V_{CC}=600\text{ V}, I_C=40\text{ A}, V_{GE}=15\text{ V}$	-	320	-	nC
IGBT Switching Characteristics						
Turn-on Delay Time	$t_{d(on)}$	$T_{VJ}=25^{\circ}\text{C},$ $V_{CC}=600\text{ V},$ $I_C=40\text{ A},$ $V_{GE}=15\text{ V},$ $R_G=10\text{ }\Omega,$ Inductive load	-	65	-	ns
Rise Time	t_r		-	110	-	
Turn-off Delay Time	$t_{d(off)}$		-	250	-	
Fall Time	t_f		-	75	-	
Turn-on Energy	E_{on}	Inductive load	-	2.1	-	mJ
Turn-off Energy	E_{off}		-	1.2	-	
Total Switching Energy	E_{ts}		-	3.3	-	
Turn-on Delay Time	$t_{d(on)}$	$T_{VJ}=175^{\circ}\text{C},$ $V_{CC}=600\text{ V},$ $I_C=40\text{ A},$ $V_{GE}=15\text{ V},$ $R_G=10\text{ }\Omega,$ Inductive load	-	60	-	ns
Rise Time	t_r		-	100	-	
Turn-off Delay Time	$t_{d(off)}$		-	360	-	
Fall Time	t_f		-	150	-	
Turn-on Energy	E_{on}	Inductive load	-	3.3	-	mJ
Turn-off Energy	E_{off}		-	2.3	-	
Total Switching Energy	E_{ts}		-	5.6	-	
Diode Characteristics						
Diode Reverse Recovery Time	t_{rr}	$T_j=25^{\circ}\text{C}, V_{CC}=600\text{ V},$ $I_F=40\text{ A}, di_F/dt=300\text{ A}/\mu\text{s}$	-	270	-	ns
Diode Reverse Recovery Charge	Q_{rr}		-	2.8	-	μC
Diode Peak Reverse Recovery Current	I_{rrm}		-	19	-	A
Diode Reverse Recovery Time	t_{rr}	$T_j=175^{\circ}\text{C}, V_{CC}=600\text{ V},$ $I_F=40\text{ A}, di_F/dt=300\text{ A}/\mu\text{s}$	-	440	-	ns
Diode Reverse Recovery Charge	Q_{rr}		-	8.5	-	μC
Diode Peak Reverse Recovery Current	I_{rrm}		-	89	-	A

Typical Electrical and Thermal Characteristics

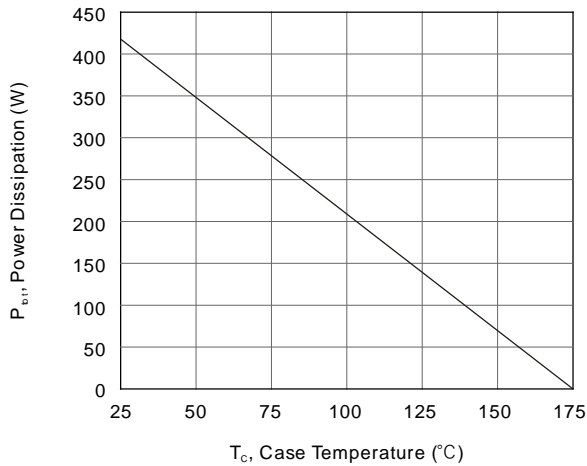


Figure 1. Power dissipation vs. case temperature
($T_{vj} \leq 175^\circ\text{C}$)

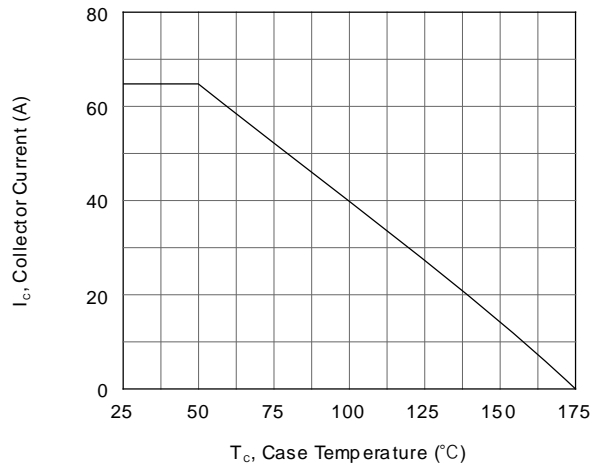


Figure 2 Collector current vs. case temperature
($V_{GE} \leq 15\text{V}$, $T_{vj} \leq 175^\circ\text{C}$)

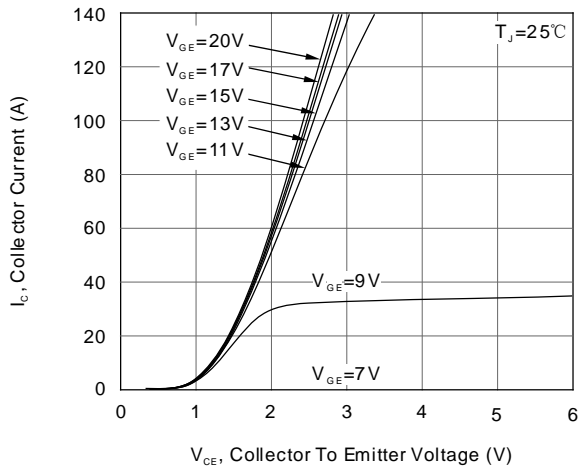


Figure 3. Typical output characteristic
($T_{vj} = 25^\circ\text{C}$)

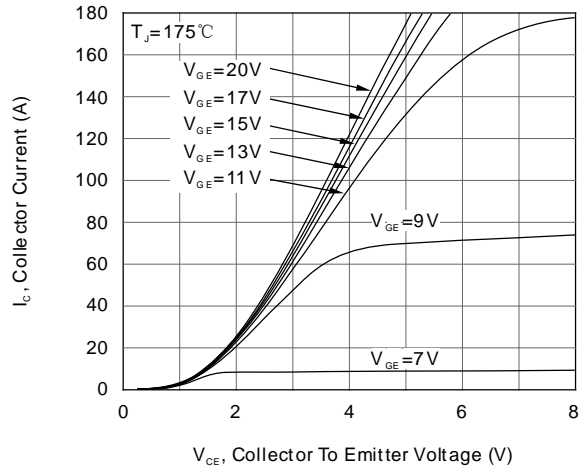


Figure 4. Typical output characteristic
($T_{vj} = 175^\circ\text{C}$)

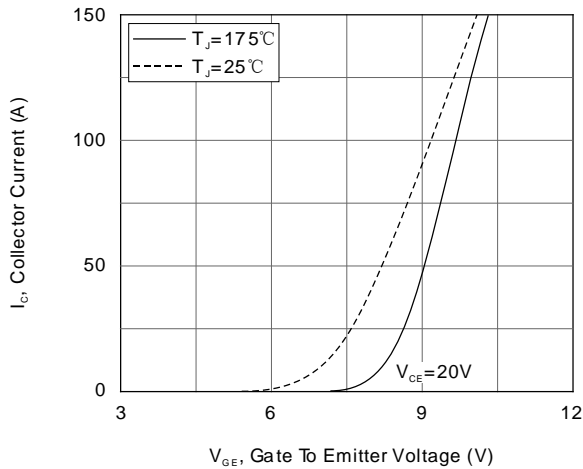


Figure 5. Typical transfer characteristic
($V_{CE} = 20\text{V}$)

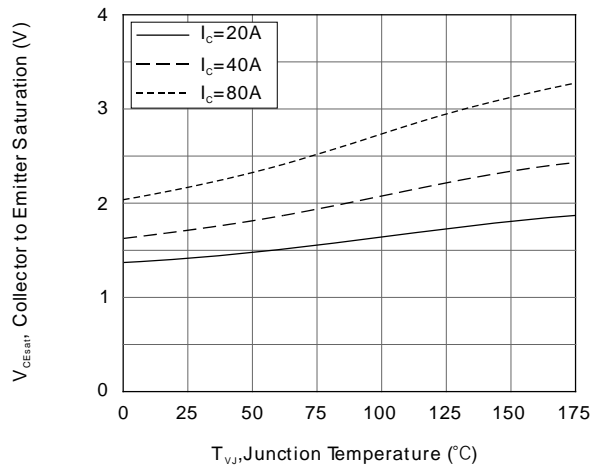


Figure 6. Typical collector-emitter saturation voltage vs. T_{vj}
($V_{GE} = 20\text{V}$)

Typical Electrical and Thermal Characteristics (cont.)

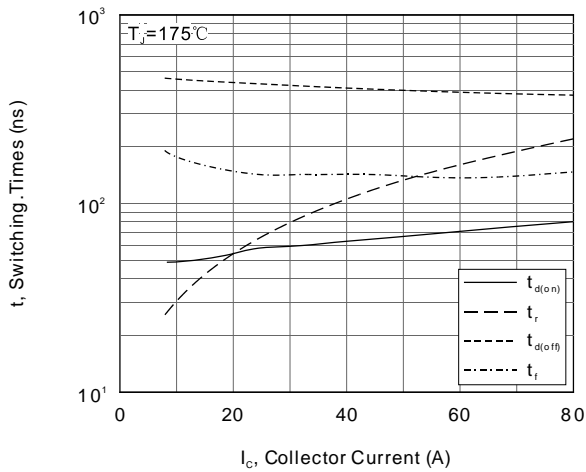


Figure 7. Typical switching times vs. collector current
(Ind. load, $T_{vj}=175^{\circ}\text{C}$, $V_{ce}=600\text{V}$, $V_{ge}=15/0\text{V}$, $R_g=12\Omega$)

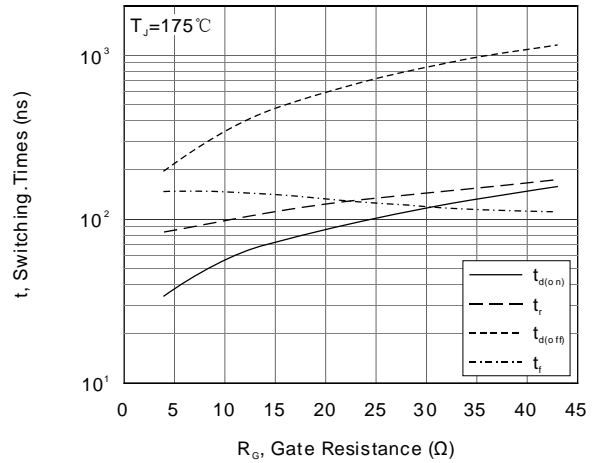


Figure 8. Typical switching times vs. gate resistor
(Ind. Load, $T_{vj}=175^{\circ}\text{C}$, $V_{ce}=600\text{V}$, $V_{ge}=15/0\text{V}$, $I_c=40\text{A}$)

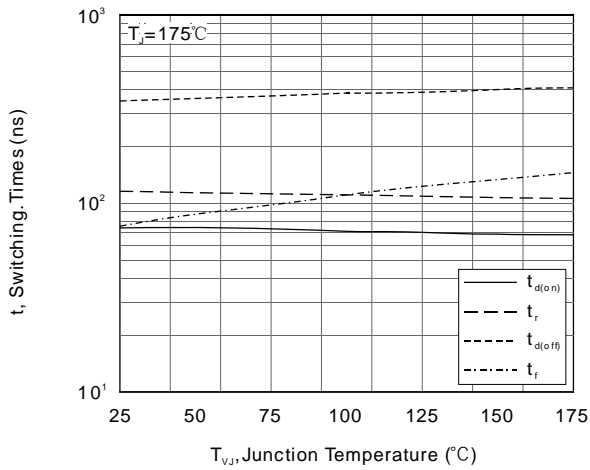


Figure 9. Typical switching times vs. T_{vj}
(Ind. Load, $V_{ce}=600\text{V}$, $V_{ge}=15/0\text{V}$, $I_c=40\text{A}$, $R_g=12\Omega$)

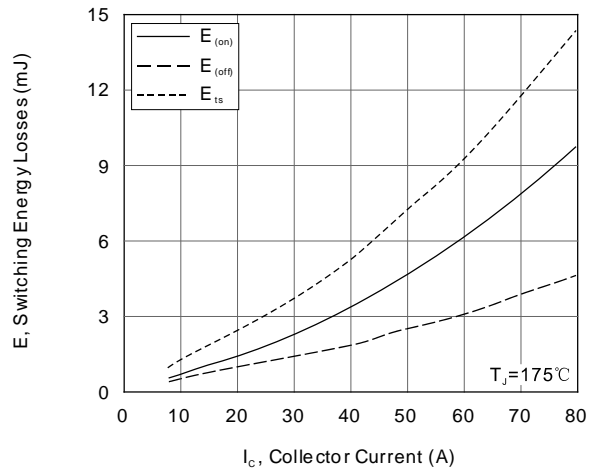


Figure 10. Typical switching energy losses vs. collector current
(Ind. load, $T_{vj}=175^{\circ}\text{C}$, $V_{ce}=600\text{V}$, $V_{ge}=15/0\text{V}$, $R_g=12\Omega$)

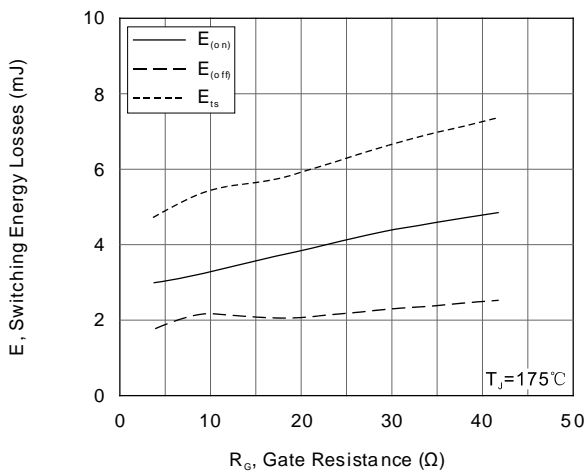


Figure 11. Typical switching energy losses vs. gate resistor
(Ind. load, $T_{vj}=175^{\circ}\text{C}$, $V_{ce}=600\text{V}$, $V_{ge}=15/0\text{V}$, $I_c=40\text{A}$)

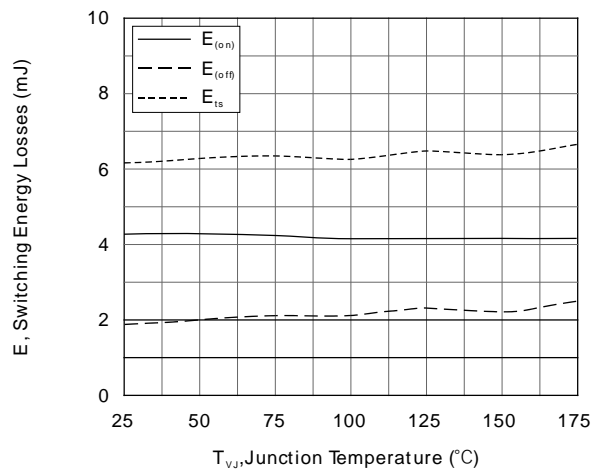


Figure 12. Typical switching energy losses vs. T_{vj}
(Ind load, $V_{ce}=600\text{V}$, $V_{ge}=15/0\text{V}$, $I_c=40\text{A}$, $R_g=12\Omega$)

Typical Electrical and Thermal Characteristics (cont.)

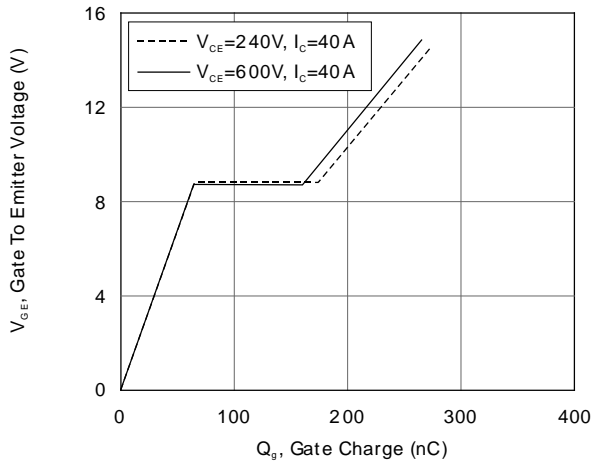


Figure 13. Typical gate charge
($I_C=40A$)

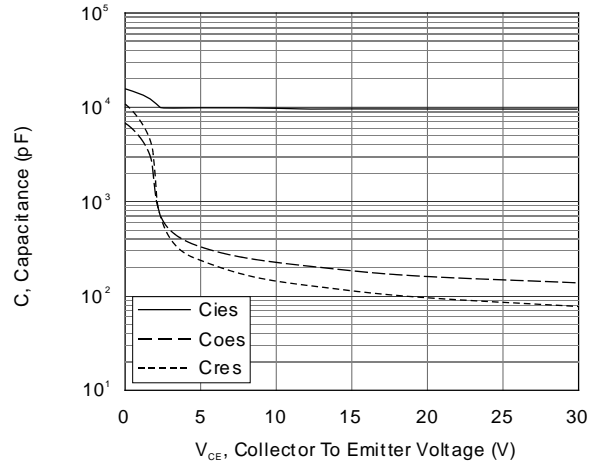


Figure 14. Typical capacitance vs. collector-emitter voltage
($V_{GE}=0V, f=1MHz$)

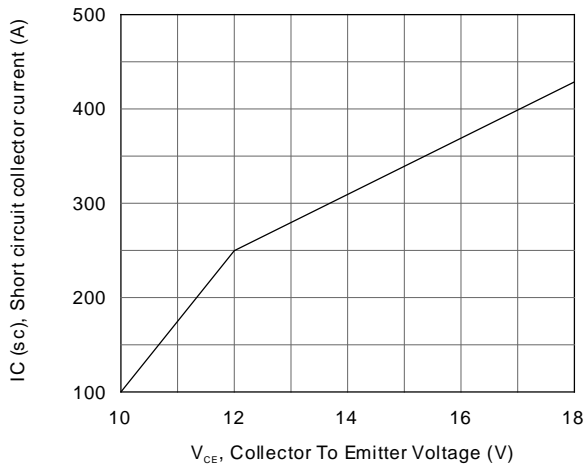


Figure 15. Typical short circuit collector current vs. gate-emitter voltage ($V_{CE} \leq 600V$ start at $T_J=25^\circ C$)

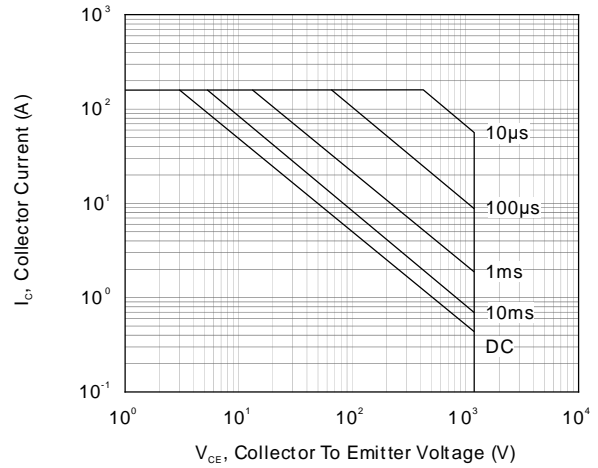


Figure 16. Forward bias safe operating area
($D=0, T_C=25^\circ C, T_{VJ} \leq 175^\circ C; V_{GE}=15V$)

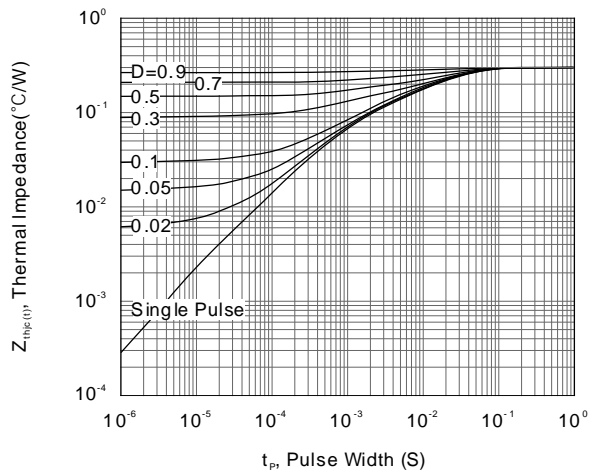


Figure 17. IGBT transient thermal impedance
($D=tp/T$)

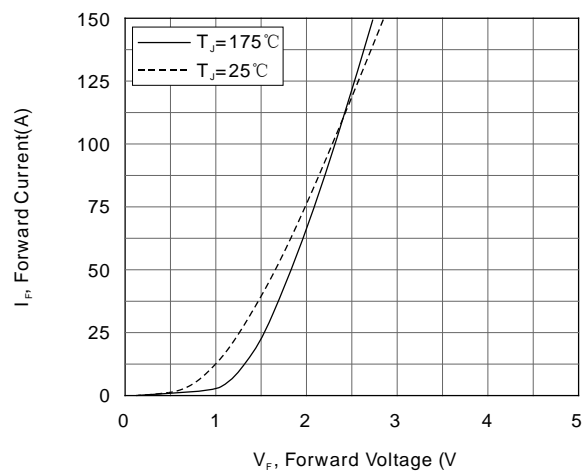


Figure 18. Typical diode forward current vs. forward voltage

Typical Electrical and Thermal Characteristics (cont.)

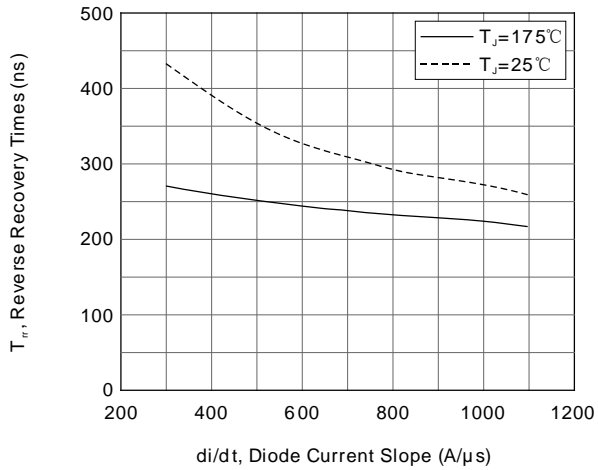


Figure 19. Typical reverse recovery time vs. diode current slope ($V_R=600V$)

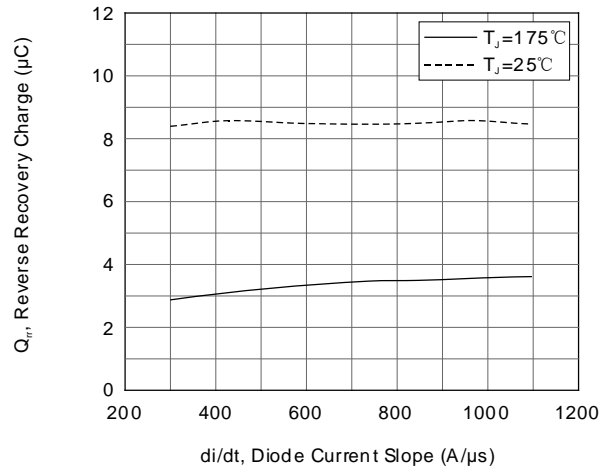


Figure 20. Typical reverse recovery charge vs. diode current slope ($V_R=600V$)

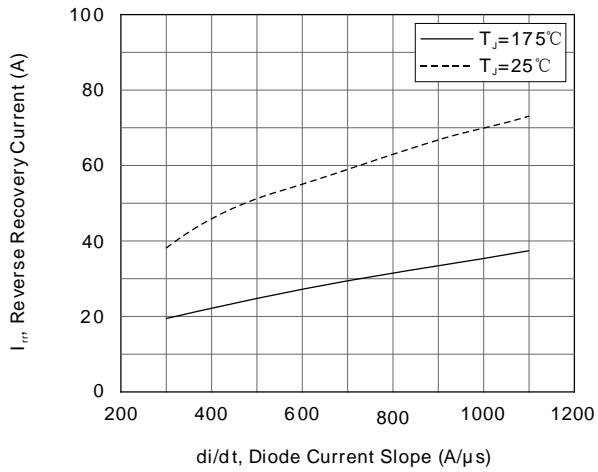
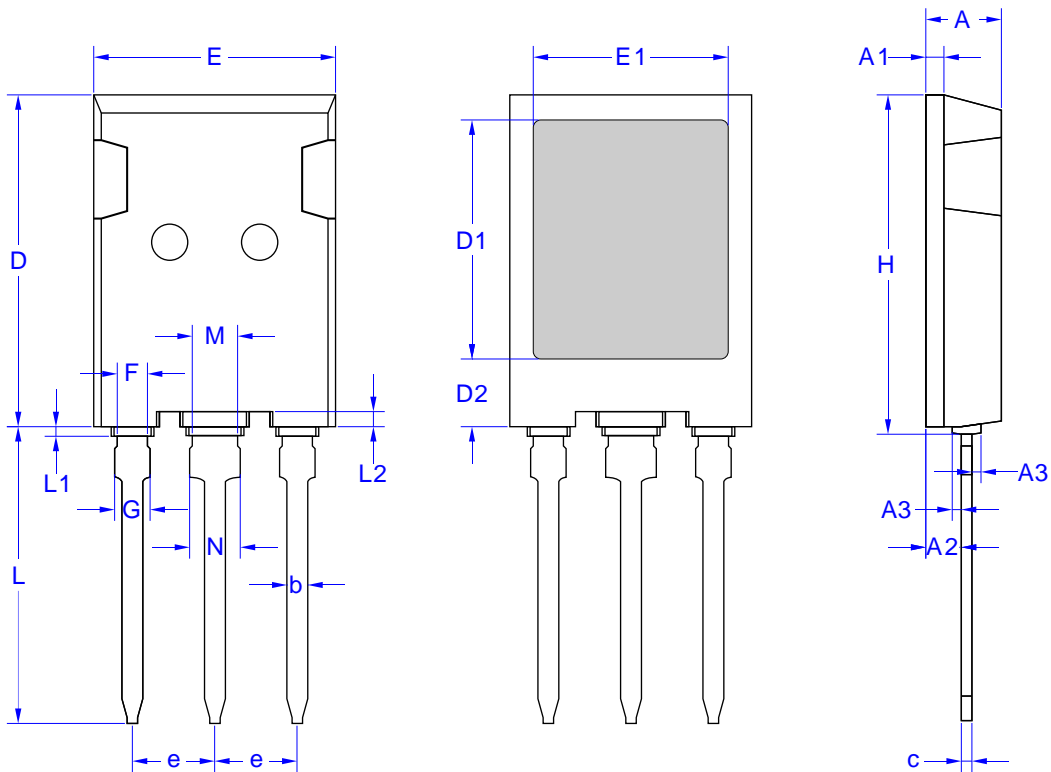


Figure 21. Typical reverse recovery current vs. diode current slope ($V_R=600V$)

Package Mechanical Data

TO-247 iPS-3L Package



Symbol	Dimensions in Millimeters		
	MIN	NOM	MAX
A	4.80	5.00	5.20
A1	1.10	1.20	1.30
A2	2.20	2.35	2.50
A3	0.45	0.60	0.75
b	1.16	1.36	1.56
c	0.51	0.70	0.89
D	21.80	22.00	22.20
D1	12.60	12.90	13.20
D2	3.55	3.75	3.95
E	15.70	16.00	16.30

Symbol	Dimensions in Millimeters		
	MIN	NOM	MAX
E1	15.55	15.85	16.15
e	5.25	5.45	5.65
F	1.80	2.00	2.20
G	2.15	2.35	2.55
H	4.80	5.00	5.20
L	19.40	19.70	20.00
L1	0.44	0.64	0.84
L2	0.80	1.00	1.20
M	2.80	3.00	3.20
N	3.15	3.35	3.55